

ULTRA LOW CAPACITANCE TVS ARRAY



DESCRIPTION

The GBLCxxI and GBLCxxCI Series are ultra low capacitance transient voltage suppressor arrays, designed to protect applications such as portable electronics and SMART phones. This series is available in both unidirectional and bidirectional configurations and is rated at 250 Watts for an 8/20µs waveshape.

The GBLCxxI and GBLCxxCI Series meets IEC 61000-4-2 (ESD) and IEC 61000-4-4 (EFT) requirements. At higher operating frequencies or faster edge rates, insertion loss and signal integrity are a major concern. This series offers a ultra low capacitance and low leakage current in a miniature SOD-323 package.

FEATURES

- Compatible with IEC 61000-4-2 (ESD): Air 15kV, Contact 8kV
 Exceeds Level 4: Handles 10kV Contact & 25kV Air Discharge
- Compatible with IEC 61000-4-4 (EFT): 40A 5/50ns
- 250 Watts Peak Pulse Power per Line (tp = 8/20μs)
- Replacement for MLV (0805)
- Unidirectional & Bidirectional Configurations
- Protects One Power or I/O Port
- ESD Protection > 25kV
- Low Clamping Voltage
- · Available in Multiple Voltages Ranging From 3V to 24V
- Ultra Low Capacitance: 0.6pF (Typical)
- RoHS Compliant
- REACH Compliant

MECHANICAL CHARACTERISTICS

- Molded JEDEC SOD-323 Package
- Approximate Weight: 5 milligrams
- Lead-Free Pure-Tin Plating (Annealed)
- Solder Reflow Temperature:

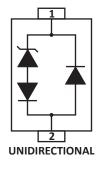
Pure-Tin - Sn, 100: 260-270°C

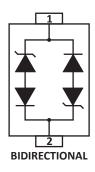
- 8mm Tape and Reel Per EIA Standard 481
- Flammability Rating UL 94V-0
- Patent Pending

APPLICATIONS

- Ethernet 10/100/1000 Base T
- SMART Phones
- Handheld Wireless Systems
- USB Interface

PIN CONFIGURATIONS







TYPICAL DEVICE CHARACTERISTICS

MAXIMUM RATINGS @ 25°C Unless Otherwise Specified							
PARAMETER	SYMBOL	VALUE	UNITS				
Peak Pulse Power (tp = 8/20μs) - See Figure 1	P _{pp}	250	Watts				
Operating Temperature	T _A	-55 to 150	°C				
Storage Temperature	T _{stg}	-55 to 150	°C				

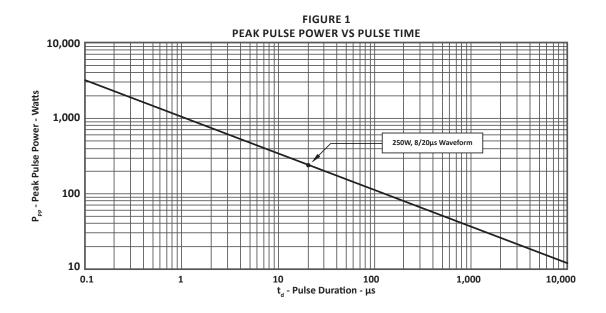
ELECTRICAL CHARACTERISTICS PER LINE @ 25°C Unless Otherwise Specified								
PART NUMBER (Note 1 -2)	DEVICE MARKING	RATED STAND-OFF VOLTAGE V _{WM} VOLTS	MINIMUM BREAKDOWN VOLTAGE @ 1mA V _(BR) VOLTS	MAXIMUM CLAMPING VOLTAGE (Fig. 2) @ IP = 1A V _c VOLTS	MAXIMUM LEAKAGE CURRENT @V _{wM} I _D μΑ	TYPICAL CAPACITANCE @0V, 1MHz C pF		
GBLC03I	С	3.0	4.0	7.0	5	0.6		
GBLC03CI	СС	3.0	4.0	7.0	5	0.6		
GBLC05I	А	5.0	6.0	9.8	5	0.6		
GBLC05CI	AC	5.0	6.0	9.8	5	0.6		
GBLC08I	В	8.0	8.5	13.4	2	0.6		
GBLC08CI	ВС	8.0	8.5	13.4	2	0.6		
GBLC12I	D	12.0	13.3	19.0	1	0.6		
GBLC12CI	DC	12.0	13.3	19.0	1	0.6		
GBLC15I	E	15.0	16.7	24.0	1	0.6		
GBLC15CI	EC	15.0	16.7	24.0	1	0.6		
GBLC18I	F	18.0	20.0	29.0	1	0.6		
GBLC18CI	FC	18.0	20.0	29.0	1	0.6		
GBLC24I	Н	24.0	26.7	43.0	1	0.6		
GBLC24CI	нс	24.0	26.7	43.0	1	0.6		

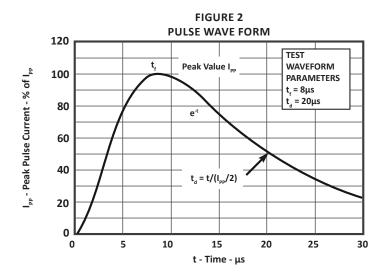
NOTES

^{1.} Part numbers with an additional "C" suffix are bidirectional devices, i.e., GBLC05 $\underline{\textbf{C}}$ I.

^{2.} Unidirectional Only: Positive potential is applied from pin 1 to 2.

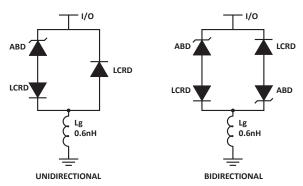
TYPICAL DEVICE CHARACTERISTICS





SPICE MODEL

FIGURE 1 SPICE MODEL



ABD - Avalanche Breakdown Diode (TVS) LCRD: Low Capacitance Rectifier Diode Lg - Lead Inductance

TABLE 1 - SPICE PARAMETERS							
PARAMETER	UNIT	ABD(TVS)	LCRD				
BV	V	See Table 2	100				
IBV	μΑ	1	0.5				
C _{jo}	pF	See Table 2	0.3				
I _s	А	See Table 2	1E-11				
Vj	V	0.6	0.6				
М	-	0.33	0.33				
N	-	1	1				
R _s	Ohms	See Table 2	0.75				
TT	S	1E-8	1E-9				
EG	eV	1.11	1.11				

TABLE 2 - ABD SPECIFIC SPICE PARAMETERS								
PART NUMBER	B _v (VOLTS)	C _{io} (pF)	I _s (AMPS)	Rs(OHMS)				
GBLC03I	4.0	200	1E-11	0.22				
GBLC05I	6.0	140	1E-11	0.18				
GBLC08I	8.5	67	1E-11	0.12				
GBLC12I	13.3	55	1E-13	1.10				
GBLC15I	16.7	47	1E-13	1.43				
GBLC18I	20.0	40	1E-13	2.30				
GBLC24I	26.7	28	1E-13	4.24				
GBLC03CI	4.0	200	1E-11	0.22				
GBLC05CI	6.0	140	1E-11	0.18				
GBLC08CI	8.5	67	1E-11	0.12				
GBLC12CI	13.3	55	1E-13	1.10				
GBLC15CI	16.7	47	1E-13	1.43				
GBLC18CI	20.0	40	1E-13	2.3				
GBLC24CI	26.7	28	1E-13	4.24				

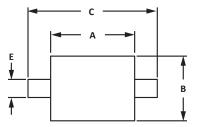


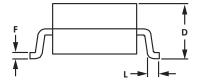
SOD-323 PACKAGE INFORMATION

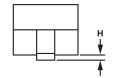
OUTLINE DIMENSIONS									
DIM	MILLIN	IETERS	INCHES						
DIM	MIN	MAX	MIN	MAX					
А	1.60	1.90	0.063	0.075					
В	1.15	1.45	0.045	0.057					
С	2.39	2.70	0.094	0.106					
D	0.80	1.10	0.031	0.043					
Е	0.25	0.40	0.010	0.016					
F	0.10	0.20	0.004	0.008					
Н	-	0.10	-	0.004					
L	0.20	-	0.008	-					

NOTES

- 1. Controlling dimension: millimeters.
- 2. Dimensioning and tolerances per ANSI Y14.5M, 1985.
- 3. Dimensions are exclusive of mold flash and metal burrs.



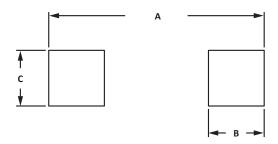




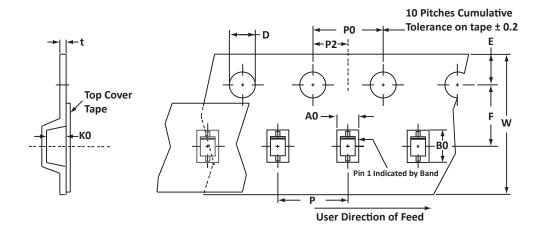
PAD LAYOUT DIMENSIONS								
DINA	MILLIM	IETERS	INCHES					
DIM	MIN MAX		MIN	MAX				
Α	2.87	3.12	0.113	0.123				
В	0.66	0.91	0.026	0.036				
С	0.66	0.91	0.026	0.036				

NOTES

1. Controlling dimension: millimeters.



TAPE AND REEL



SPECIFICATIONS												
REEL DIA.	TAPE WIDTH	A0	В0	КО	D	E	F	W	P0	P2	Р	tmax
178mm (7")	8mm	1.55 ± 0.10	2.90 ± 0.10	1.35 ± 0.10	1.50 ± 0.10	1.75 ± 0.10	3.50 ± 0.05	8.00 ± 0.30	4.00 ± 0.10	2.00 ± 0.05	4.00 ± 0.10	0.25

NOTES

- 1. Dimensions are in millimeters.
- 2. Surface mount product is taped and reeled in accordance with EIA-481.
- 3. Suffix T7 = 7" Reel 3,000 pieces per 8mm tape.
- 4. Marking on Part marking code (see page 2), polarity band (Unidirectional Only).

ORDERING INFORMATION								
BASE PART NUMBER (xx = Voltage)	LEADFREE SUFFIX	TAPE SUFFIX	QTY/REEL	REEL SIZE	TUBE QTY			
GBLCxxI/GBLCxxCI	-LF	-T7	3,000	7"	n/a			
This device is only available in a Lead-Free configuration.								



COMPANY INFORMATION

COMPANY PROFILE

In business more than 25 years, ProTek Devices™ is a privately held semiconductor company. The company offers a product line of overvoltage protection and overcurrent protection components. These include transient voltage suppressor array (TVS arrays) avalanche breakdown diode, steering diode TVS array and electronics SMD chip fuses. These components deliver circuit protection in electronic systems from numerous overvoltage and overcurrent events. They include lightning; electrostatic discharge (ESD); nuclear electromagnetic pulses (NEMP); inductive switching; and electromagnetic interference (EMI) / radio frequency interference (RFI). ProTek Devices also offers LED wafer die for ESD protection and related high frequency products. ProTek Devices is ISO 9001:2015 certified.

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